

**Notice of References Cited**Application/Control No.  
09/510,828Applicant(s)/Patent Under  
Reexamination  
HEMBREE ET AL.9Examiner  
James MitchellArt Unit  
2827

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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**NON-PATENT DOCUMENTS**

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.